

# HCM1A0703V2

## Automotive grade high current power inductors



### Product features

- AEC-Q200 qualified
- High current carrying capacity
- Magnetically shielded, low EMI
- DC-DC converter applications up to 1 MHz
- Filtering applications up to Self Resonant Frequency (SRF) [See product specification table]
- Inductance range from 0.10 µH to 33 µH
- Current range from 1.6 A to 54 A
- 7.3 mm x 6.8 mm footprint surface mount package in a 3.0 mm height
- Moisture Sensitivity Level (MSL): 1
- Alloy powder core material

### Applications

- Body electronics
  - Central body control module
  - Vehicle access control system
  - Headlamps, tail lamps and interior lighting and LED lighting
  - Heating ventilation and air conditioning controllers (HVAC)
  - Doors, window lift and seat control
- Advanced driver assistance systems
  - 77 GHz radar system
  - Adaptive cruise control (ACC)
  - Automatic parking control
  - Collision avoidance system/ Car black box system
- Infotainment and cluster electronics
  - Active noise cancellation (ANC)
  - Audio subsystem: head unit and trunk amp
  - Digital instrument cluster
  - In-vehicle infotainment (IVI) and navigation
  - Port power/USB HUB for front and rear passengers
- Chassis and safety electronics
  - Airbag control unit
  - Electronic stability control system (ESC)
- Engine and Powertrain Systems
  - Electric pumps, motor control and auxiliaries
  - Powertrain control module (PCU)/ Engine Control unit (ECU)
  - Transmission Control Unit (TCU)

### Environmental data

- Storage temperature range (Component): -55 °C to +155 °C
- Operating temperature range: -55 °C to +155 °C (ambient plus self-temperature rise)
- Solder reflow temperature: J-STD-020 (latest revision) compliant



## Product specifications

Part number <sup>6</sup>	OCL <sup>1</sup> ( $\mu$ H) $\pm$ 20%	FLL <sup>2</sup> ( $\mu$ H) minimum	I <sub>rms</sub> <sup>3</sup> (A)	I <sub>sat</sub> <sup>4</sup> (A)	DCR (m $\Omega$ ) typical @ +20 °C	DCR (m $\Omega$ ) maximum @ +20 °C	SRF (MHz) typical	K-factor <sup>5</sup>
HCM1A0703V2-R10-R	0.10	0.064	29	54	0.63	0.8	350	1284
HCM1A0703V2-R15-R	0.15	0.090	24	30	1.03	1.3	195	1541
HCM1A0703V2-R22-R	0.22	0.130	18	32	1.8	2.3	150	1039
HCM1A0703V2-R33-R	0.33	0.210	15	19	2.9	3.5	95	823
HCM1A0703V2-R47-R	0.47	0.300	13	17	3.7	4.14	70	713
HCM1A0703V2-R56-R	0.56	0.350	13	12	3.8	4.5	60	805
HCM1A0703V2-R68-R	0.68	0.430	12	13	4.8	5.5	57	843
HCM1A0703V2-R82-R	0.82	0.520	10	14	5.7	6.6	55	608
HCM1A0703V2-1R0-R	1.0	0.64	10	9.0	6.5	7.8	48	627
HCM1A0703V2-1R2-R	1.2	0.76	9	12	8.6	9.9	35	434
HCM1A0703V2-1R5-R	1.5	0.96	8.5	10	9.5	11.5	35	445
HCM1A0703V2-2R2-R	2.2	1.40	7.0	8.5	12.5	15.5	29	532
HCM1A0703V2-3R3-R	3.3	2.10	5.0	7.5	24.5	28.5	25	281
HCM1A0703V2-4R7-R	4.7	3.00	4.0	6.8	40.3	46.5	20	227
HCM1A0703V2-6R8-R	6.8	4.30	3.6	5.6	54	65	16	276
HCM1A0703V2-8R2-R	8.2	5.20	3.5	4.8	53	64	14	173
HCM1A0703V2-100-R	10	6.40	3.3	4.4	65	75	12	177
HCM1A0703V2-150-R	15	9.60	2.6	3.6	96	110	9.5	147
HCM1A0703V2-220-R	22	14.1	2.0	2.9	135	149	7.0	134
HCM1A0703V2-330-R	33	19.8	1.6	2.3	200	242	6.5	92

1. Open Circuit Inductance (OCL) Test Parameters: 100 kHz, 0.25 V<sub>ms</sub>, 0.0 Adc, +25 °C

2. Full Load Inductance (FLL) Test Parameters: 100 kHz, 0.25 V<sub>ms</sub>, I<sub>sat</sub>, +25 °C

3. I<sub>rms</sub>: DC current for an approximate temperature rise of 30 °C without core loss. Derating is necessary for AC currents.

PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed +155 °C under worst case operating conditions verified in the end application.

4. I<sub>sat</sub>: Peak current for approximately 20% rolloff @ +25 °C

5. K-factor: Used to determine B<sub>p-p</sub> for core loss (see graph). B<sub>p-p</sub> = K \* L \* ΔI. B<sub>p-p</sub>: (Gauss), K: (K-factor from table), L: (Inductance in  $\mu$ H), ΔI: Peak to peak ripple current in Amps.

6. Part Number Definition: HCM1A0703V2-xxx-R

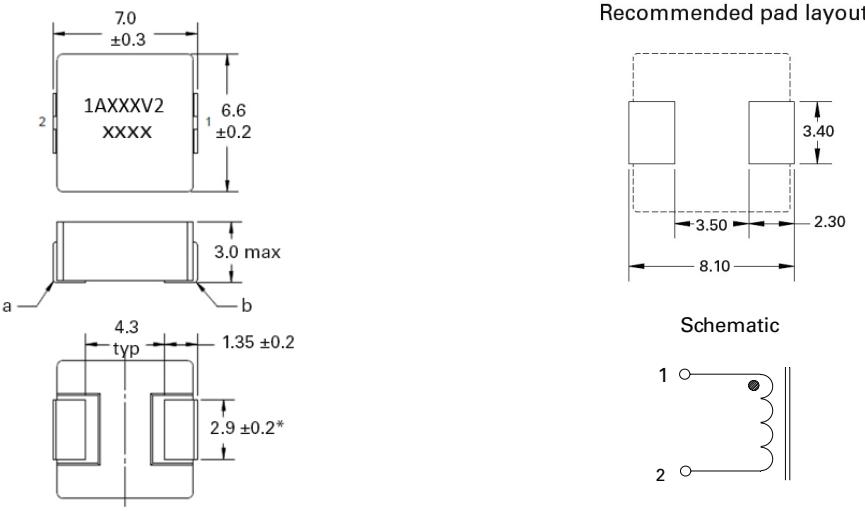
HCM1A0703V2 = Product code and size

xxx= inductance value in  $\mu$ H, R= decimal point,

If no R is present then last character equals number of zeros

-R suffix = RoHS compliant

## Dimensions (mm)

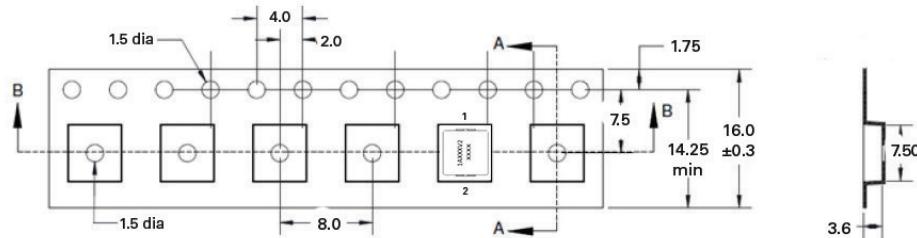


Part marking: 1AxxxxV2, xxxx=inductance value in uH, R=decimal point. If no R is present then last character equals number of zeros. xxxx=Lot code  
 All soldering surfaces to be coplanar within 0.1 millimeters  
 Tolerances are  $\pm$ 0.3 millimeters unless stated otherwise  
 Pad layout tolerances are  $\pm$ 0.1 millimeters unless stated otherwise  
 DCR measured from point "a" to point "b"  
 Do not route traces or vias underneath the inductor

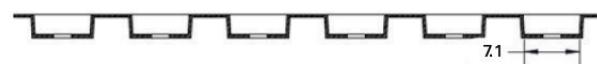
**Packaging information (mm)**

Drawing not to scale

Supplied in tape and reel packaging, 2000 parts per 13" diameter reel



Section A-A

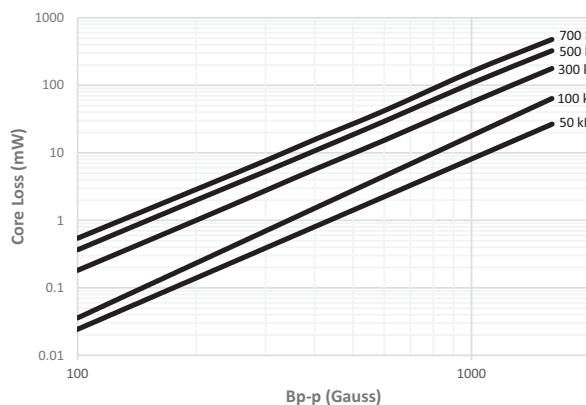


Section B-B

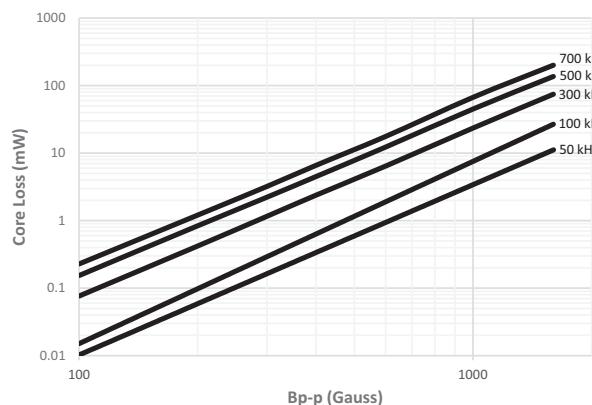
User direction of unreeling →

**Core loss vs  $B_{p-p}$** 

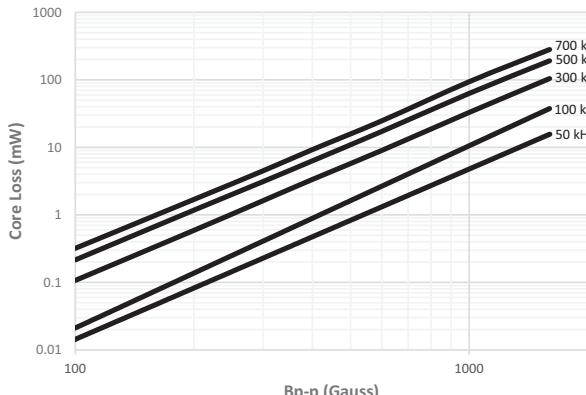
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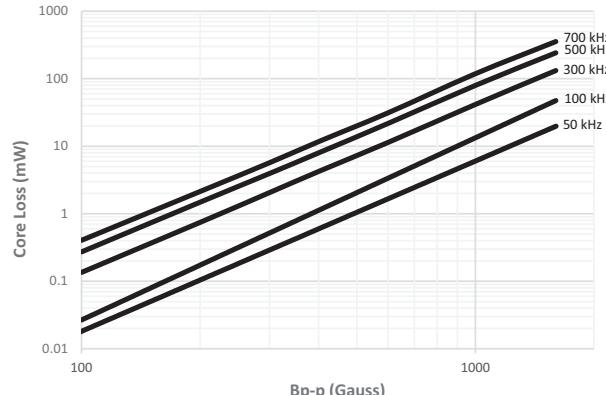
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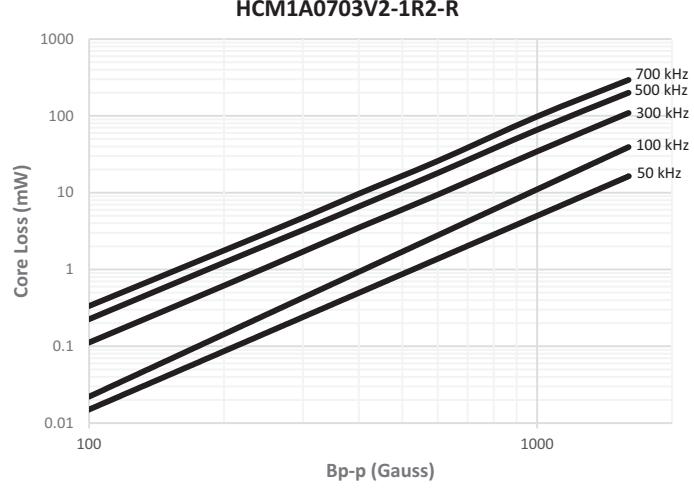
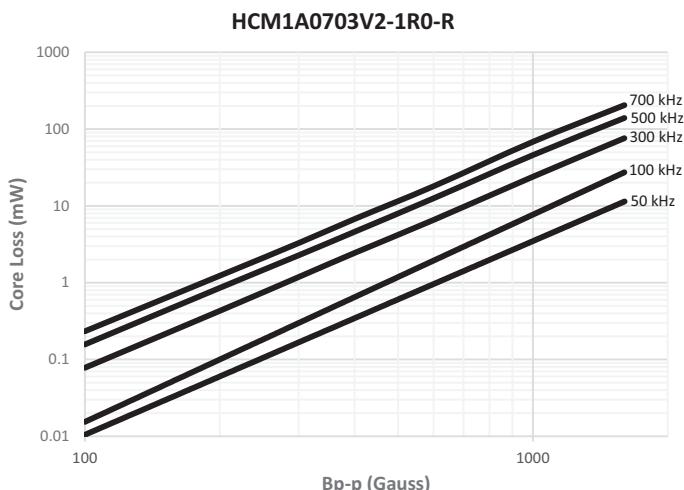
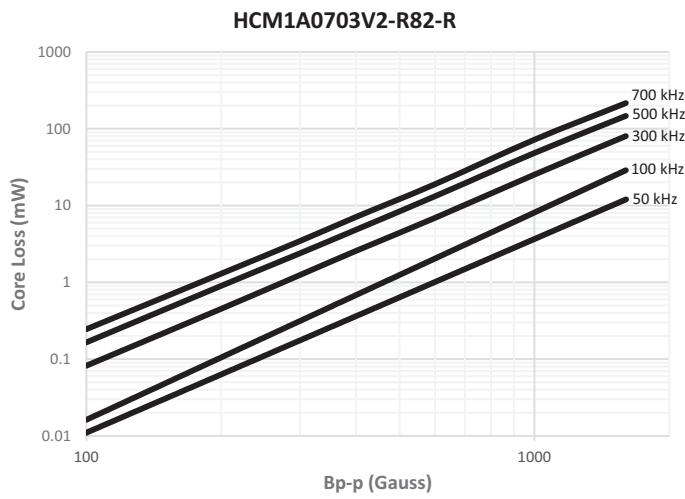
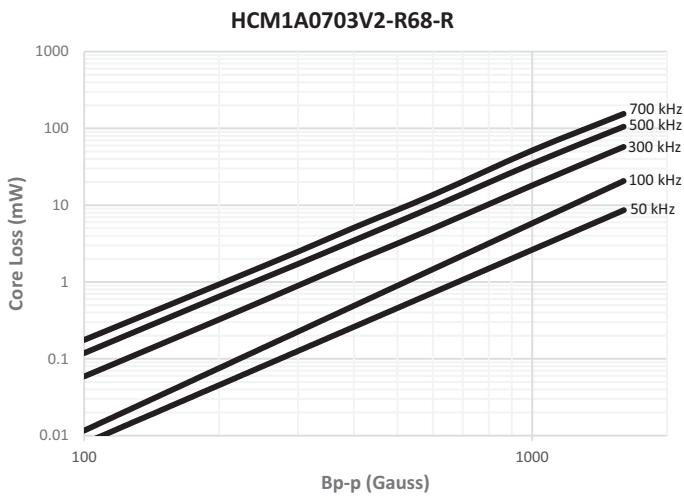
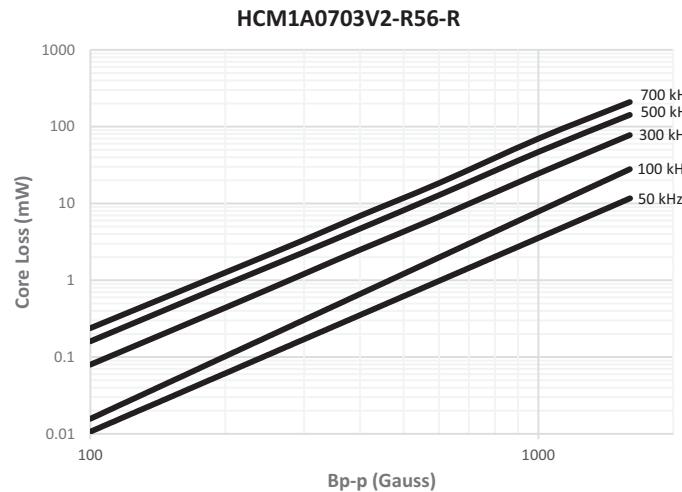
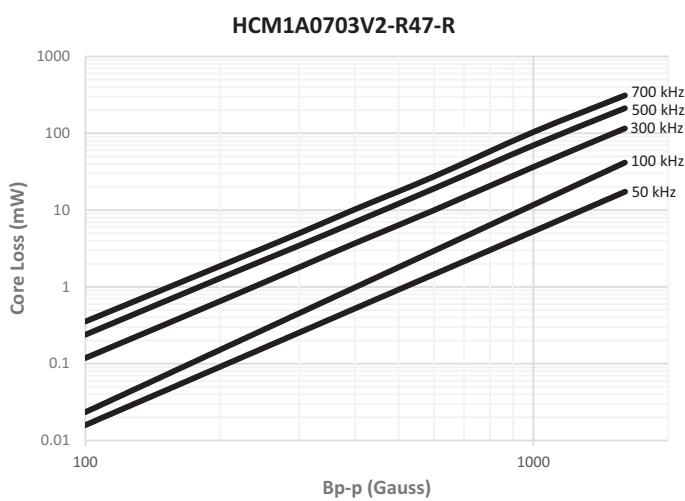
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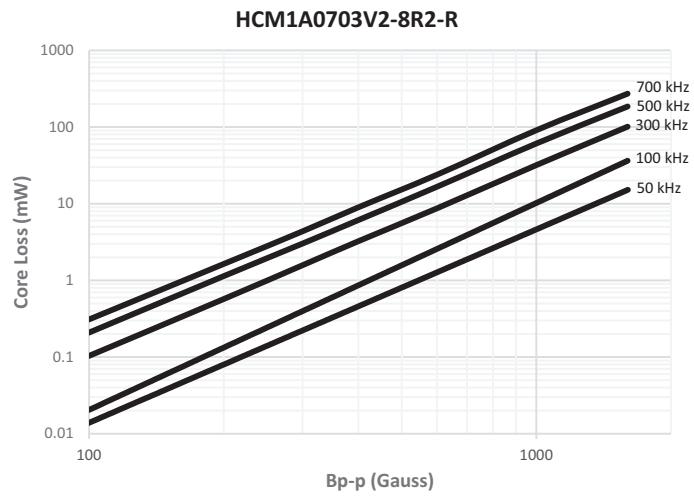
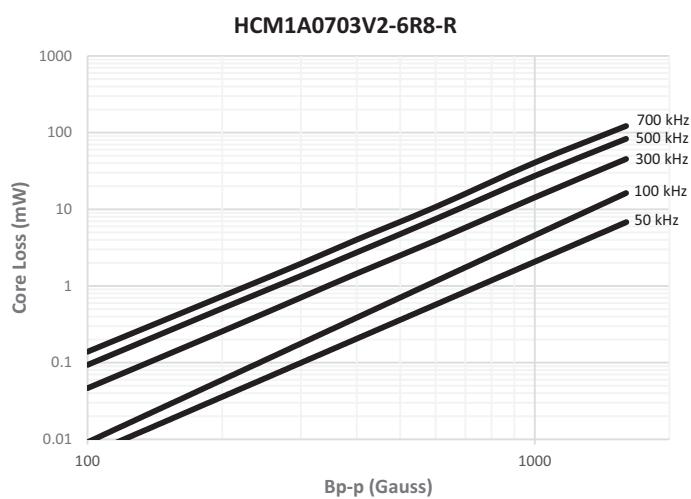
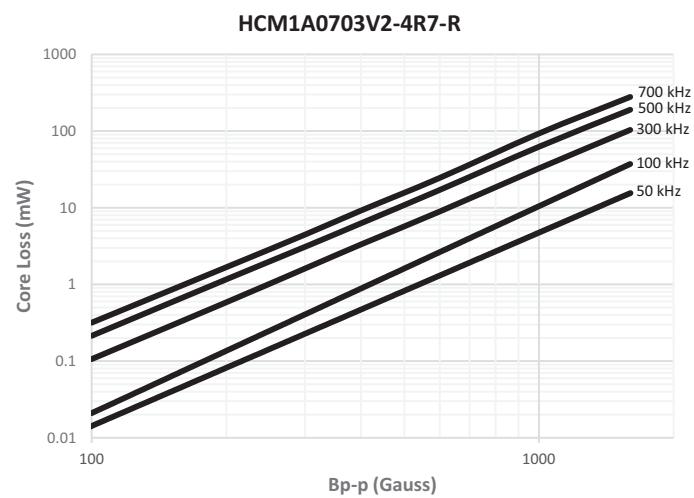
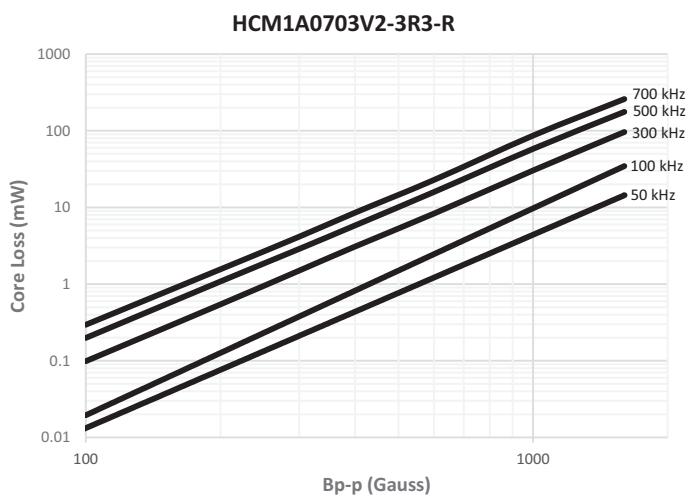
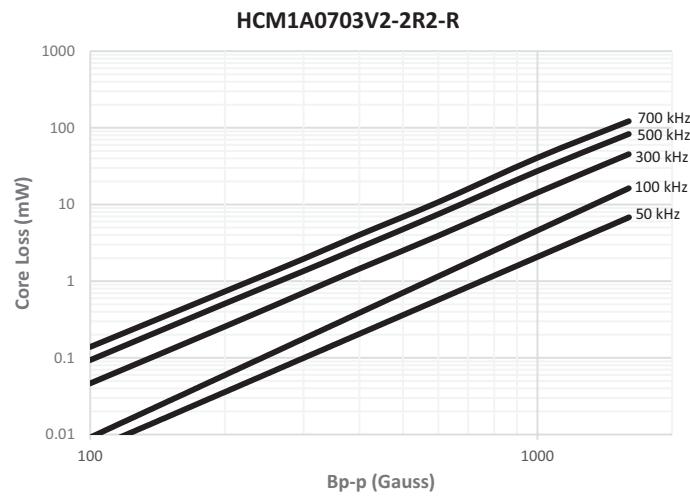
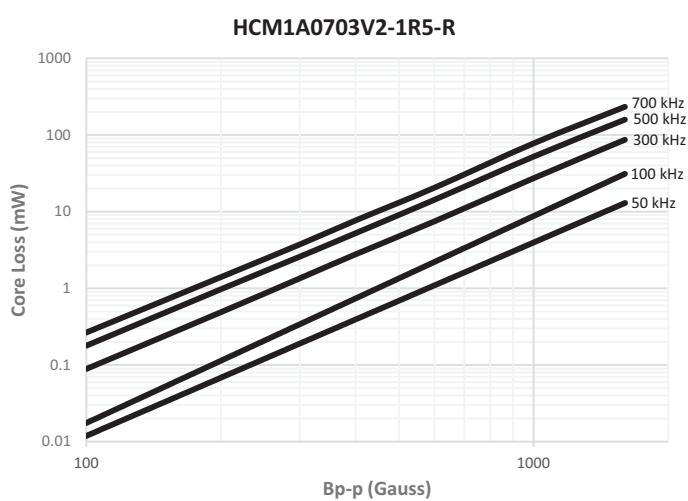
HCM1A0703V2-R33-R



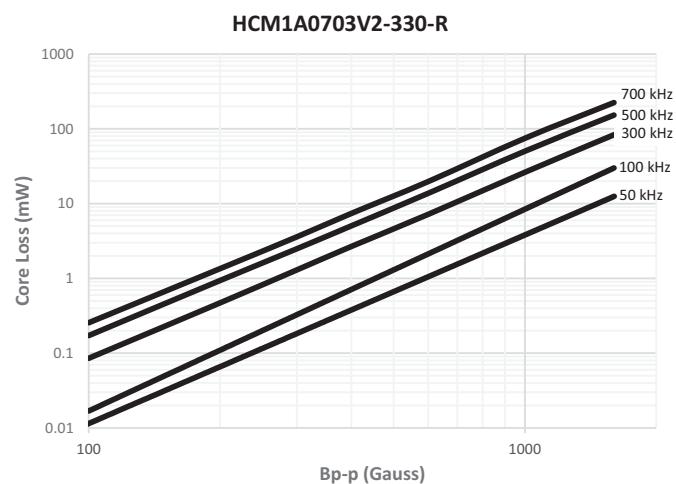
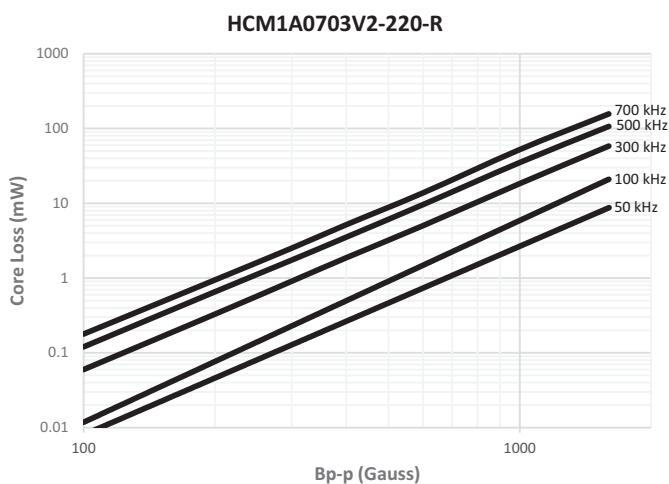
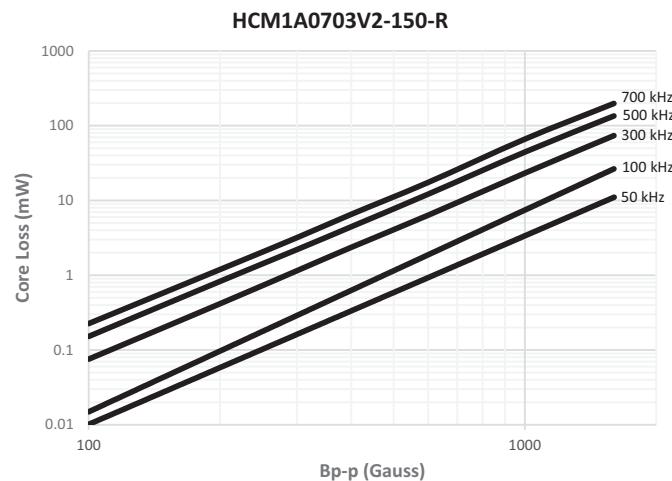
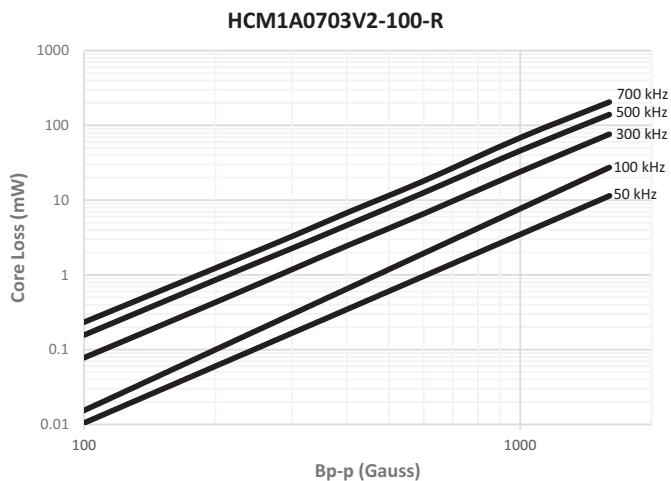
**Core loss vs B<sub>p-p</sub>**

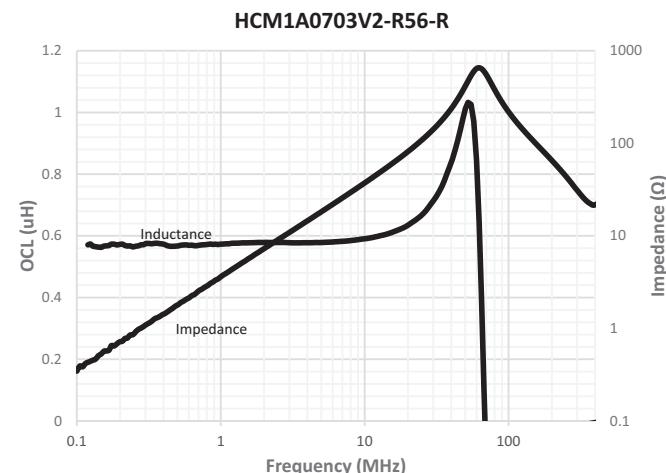
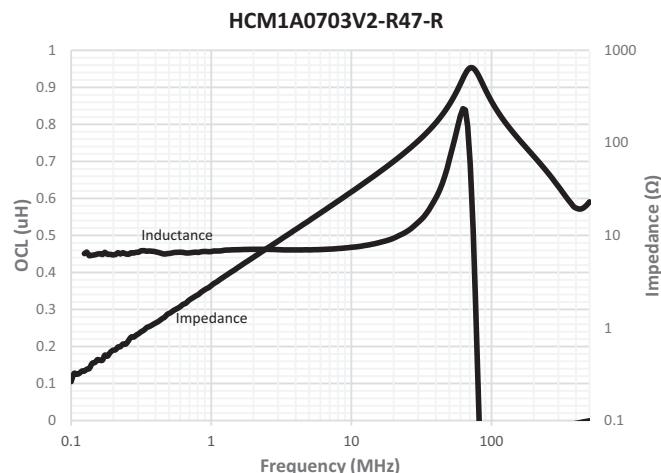
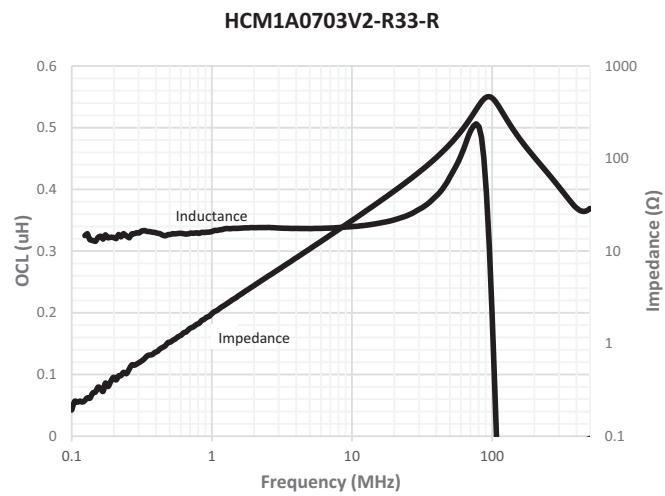
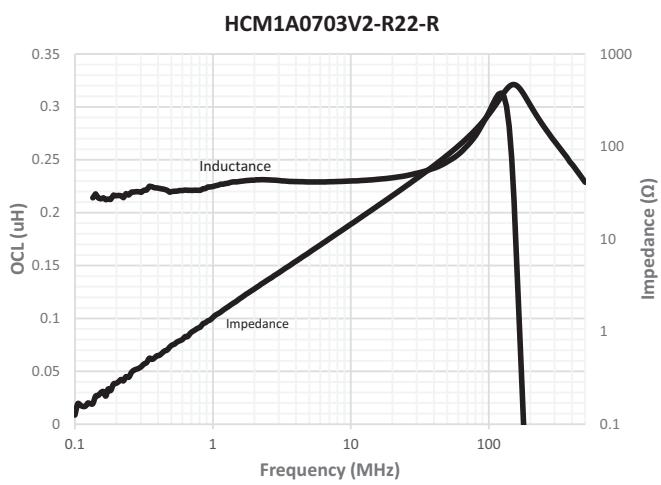
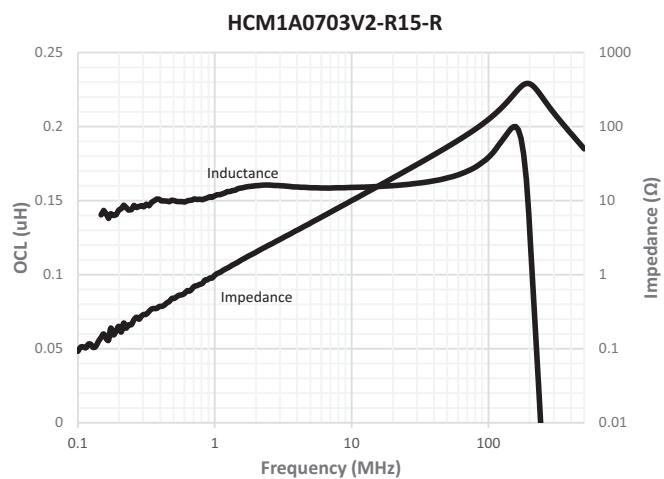
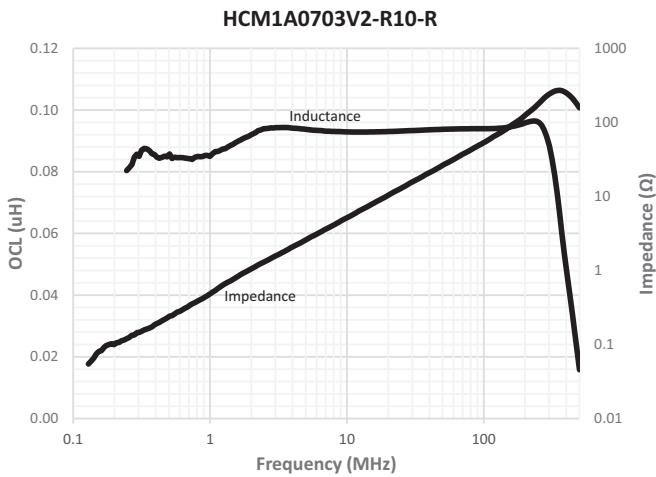


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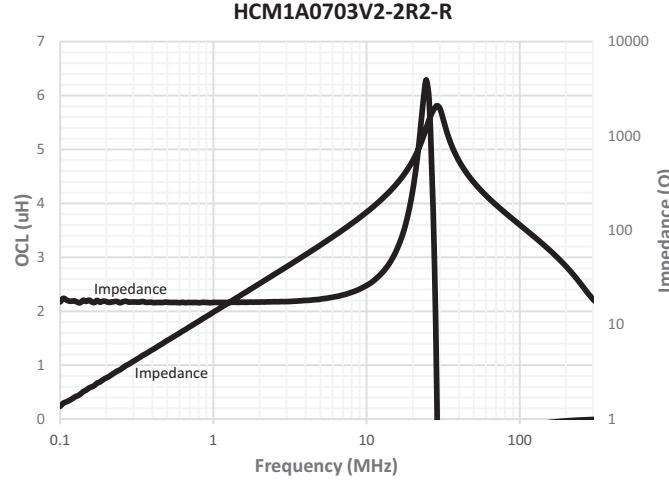
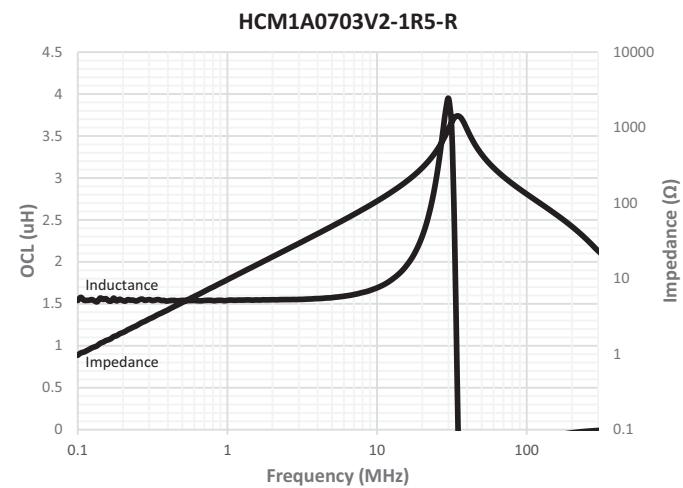
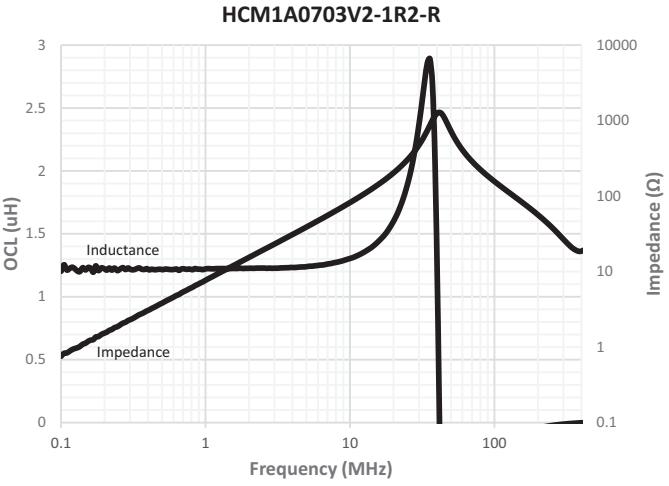
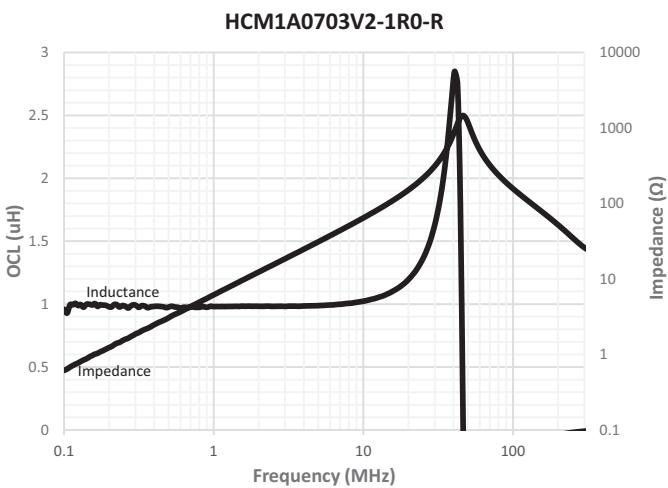
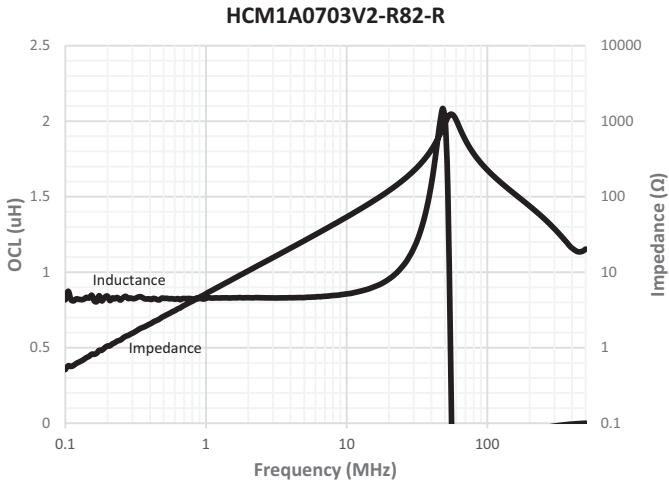
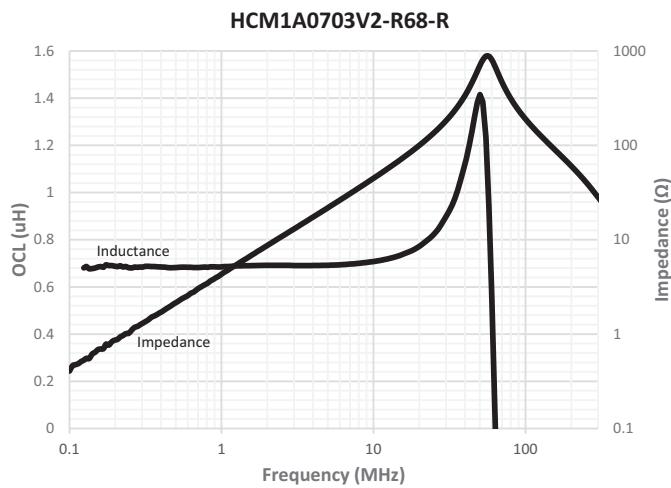


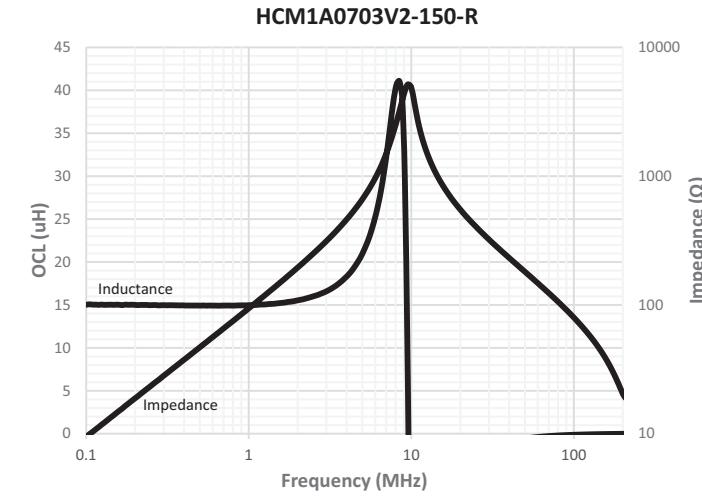
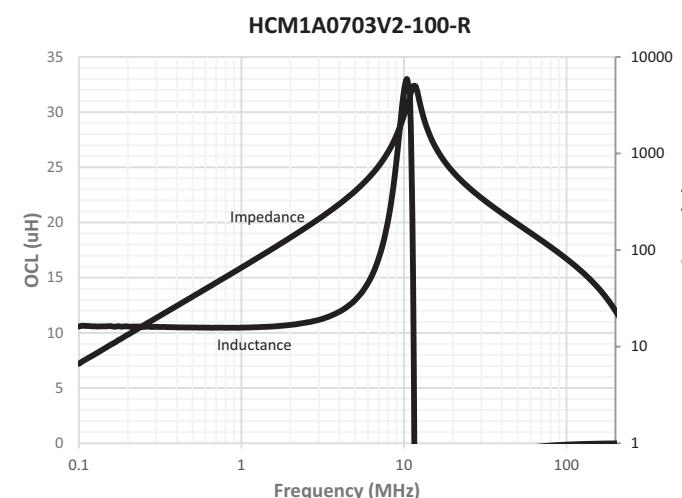
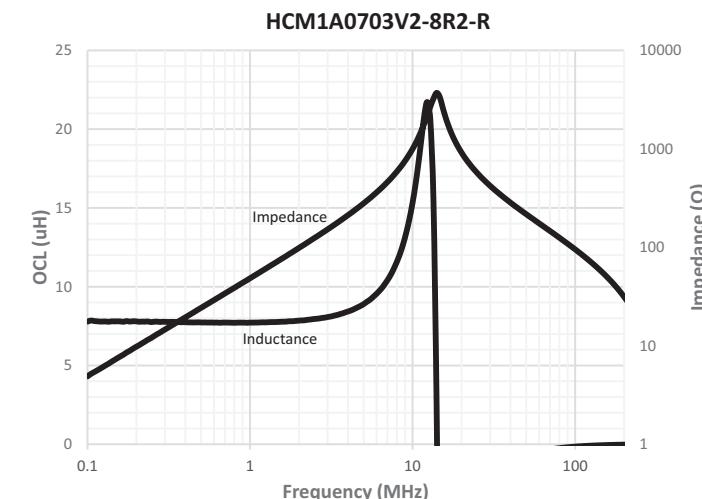
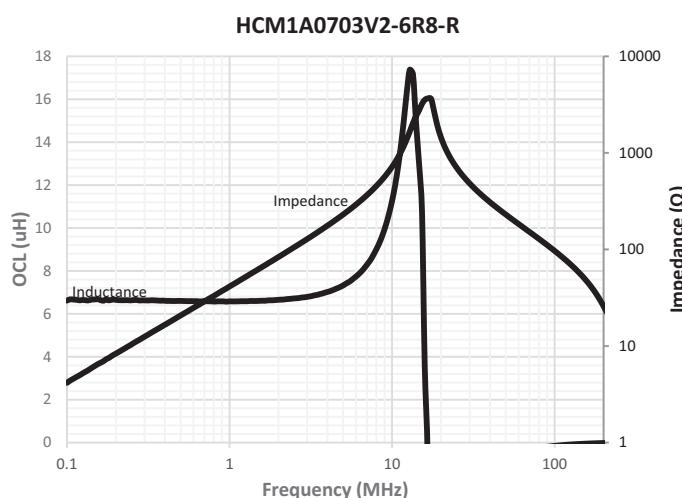
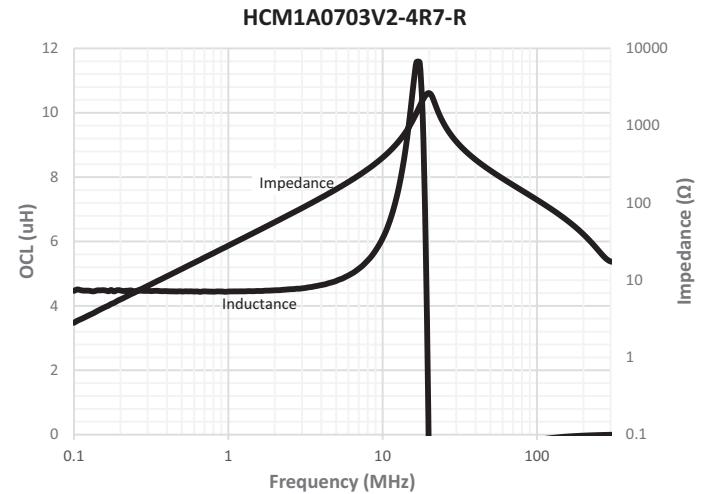
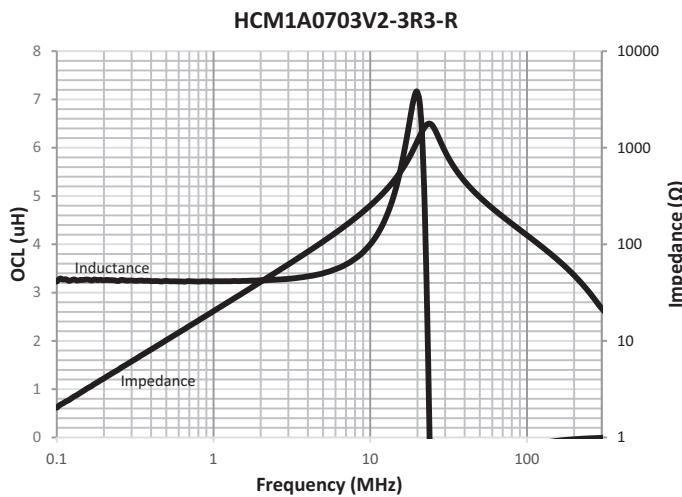
**Core loss vs B<sub>p-p</sub>**



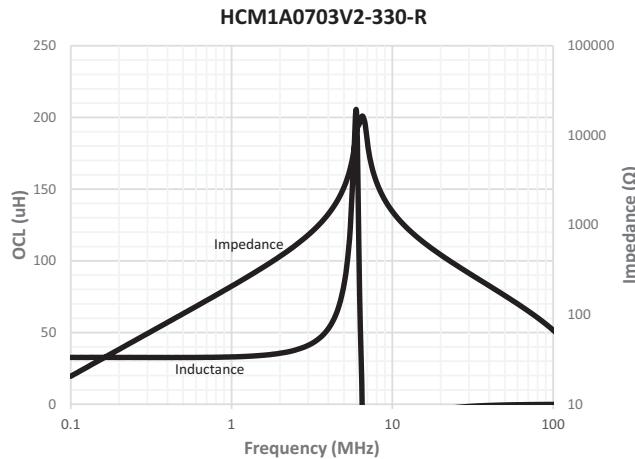
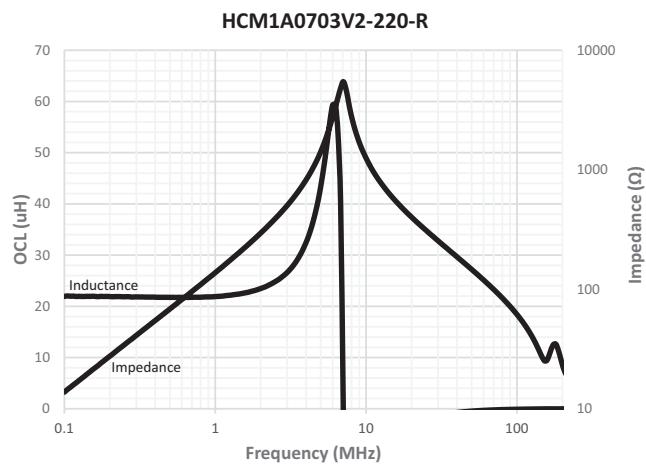
**Inductance and impedance vs. frequency**

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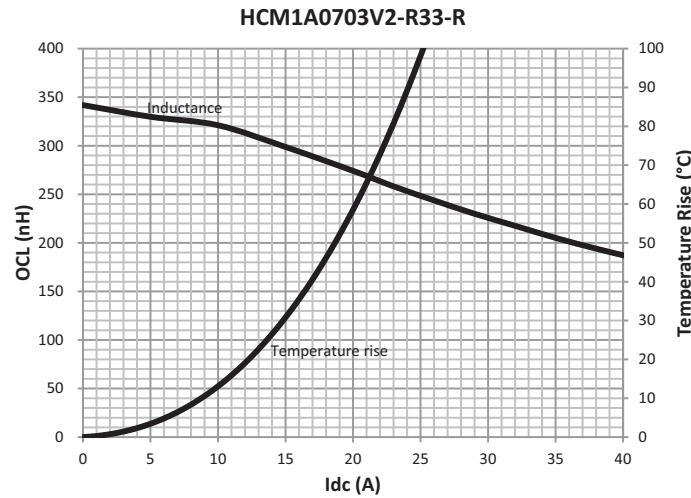
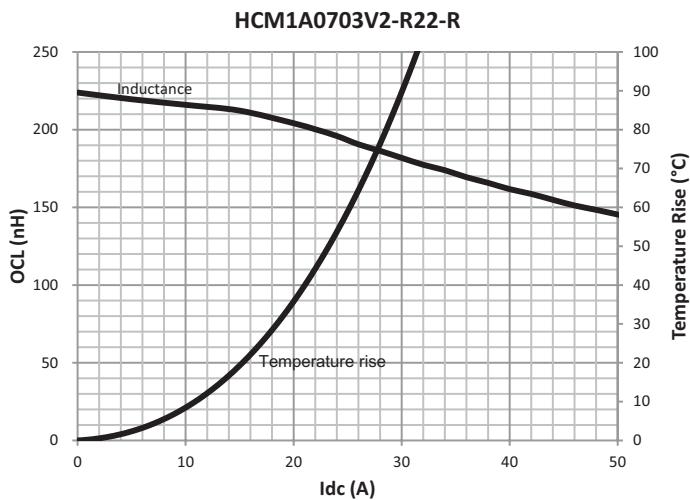
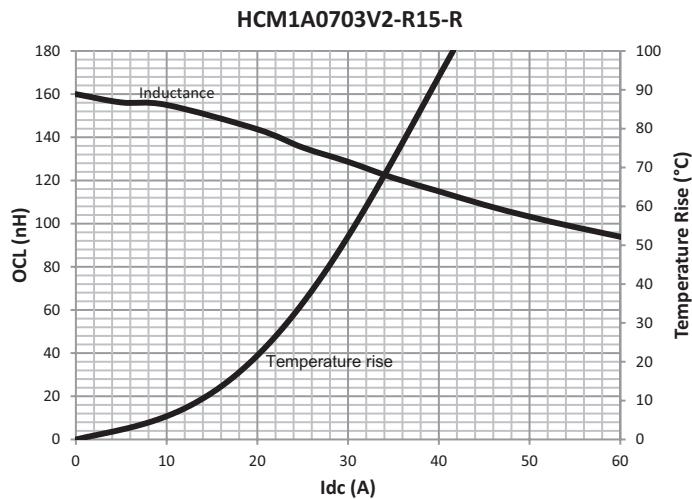
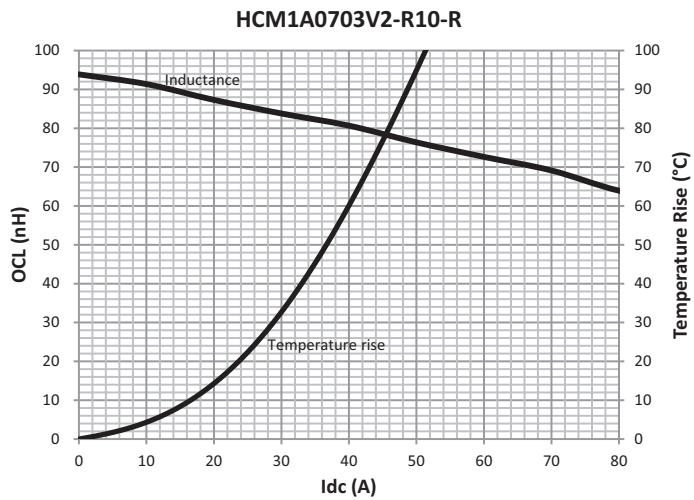


**Inductance and impedance vs. frequency**

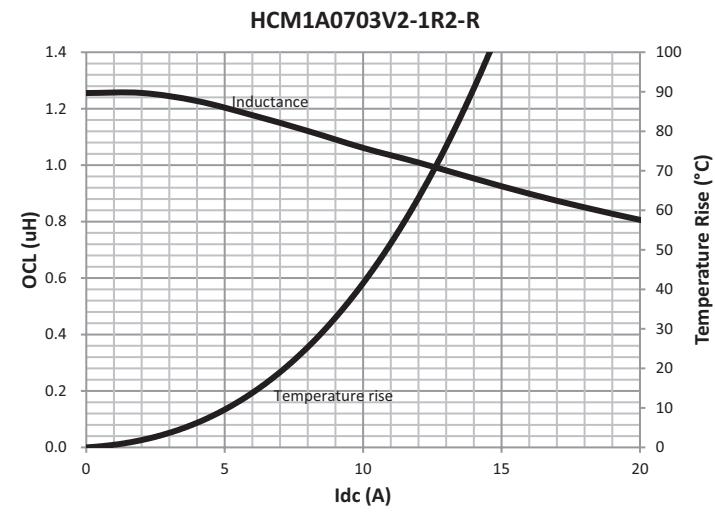
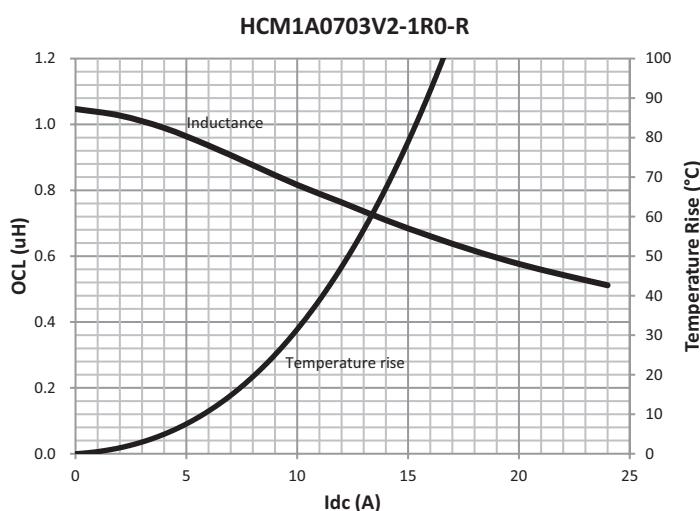
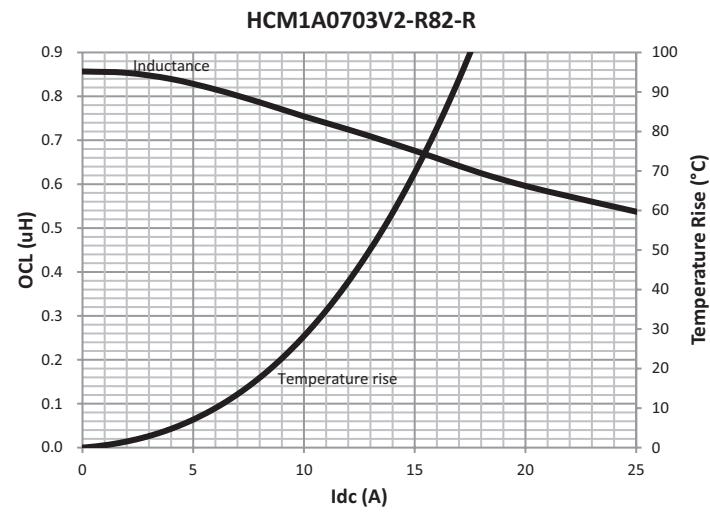
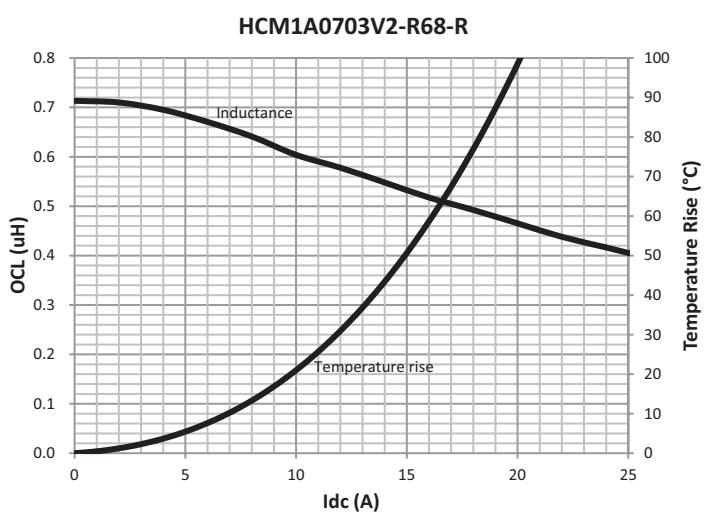
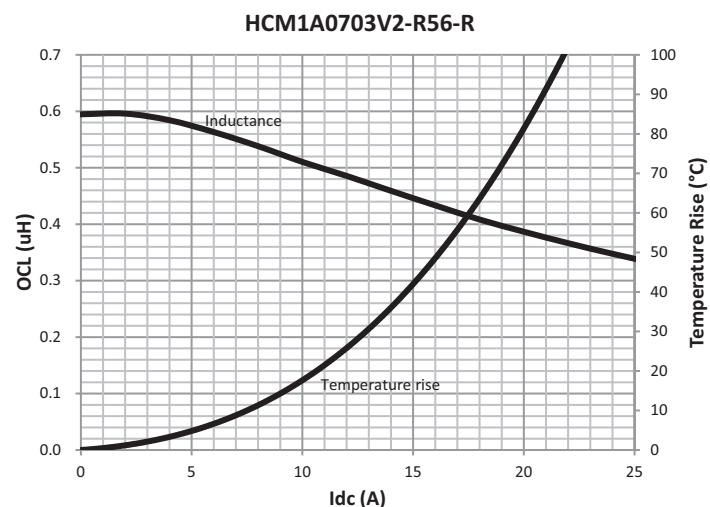
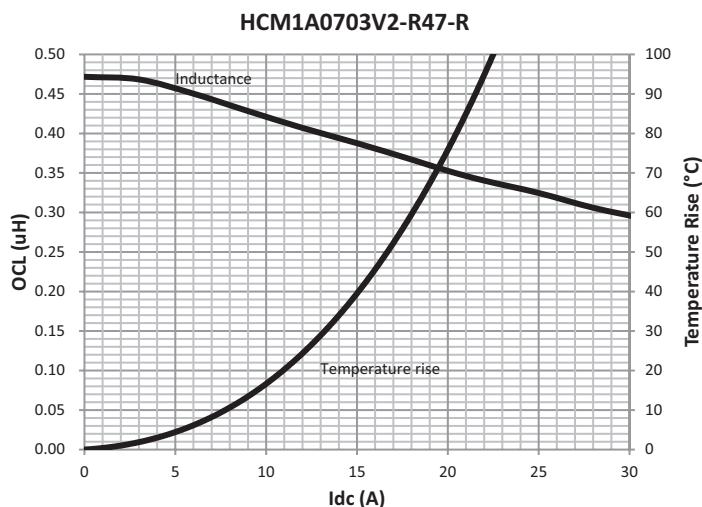
### Inductance and impedance vs. frequency



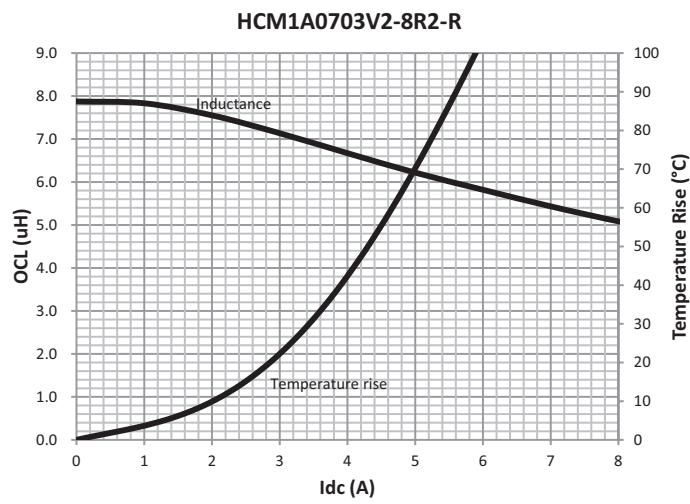
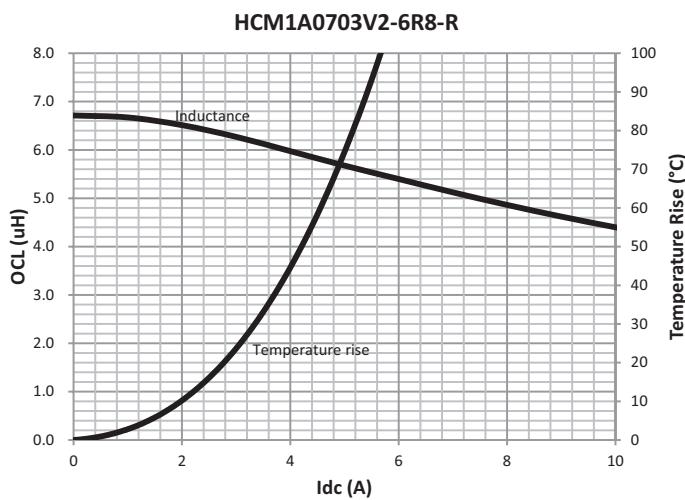
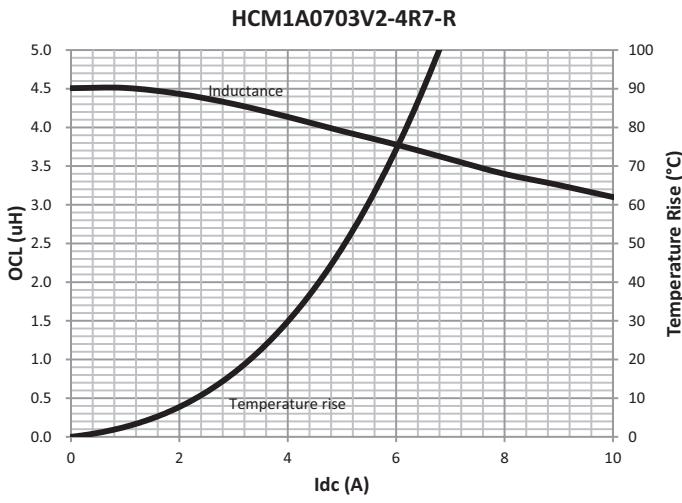
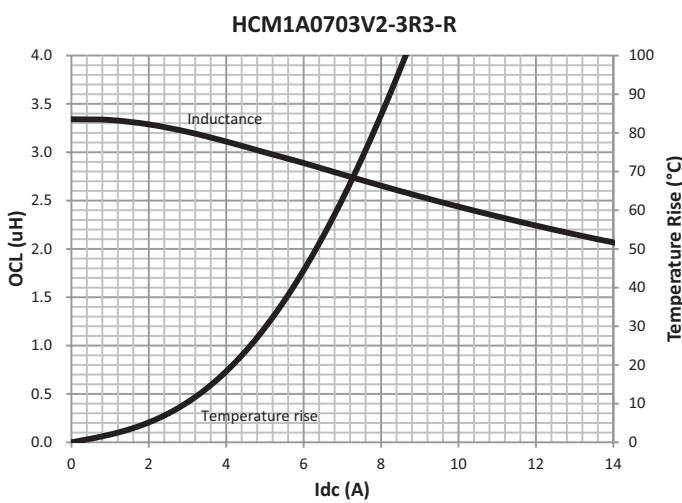
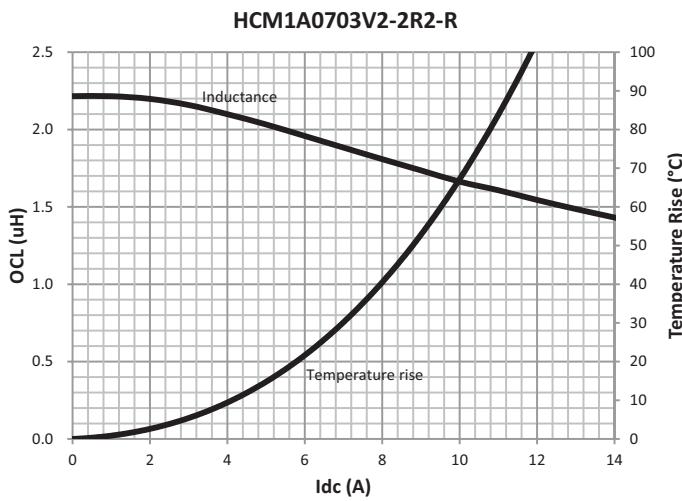
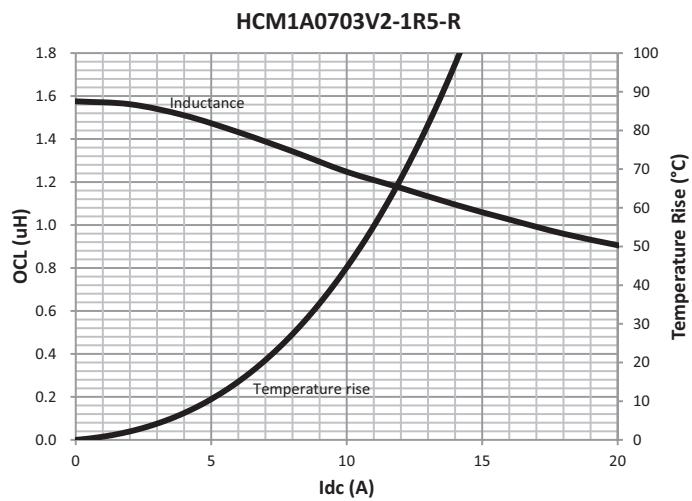
### Inductance and temperature rise vs. current

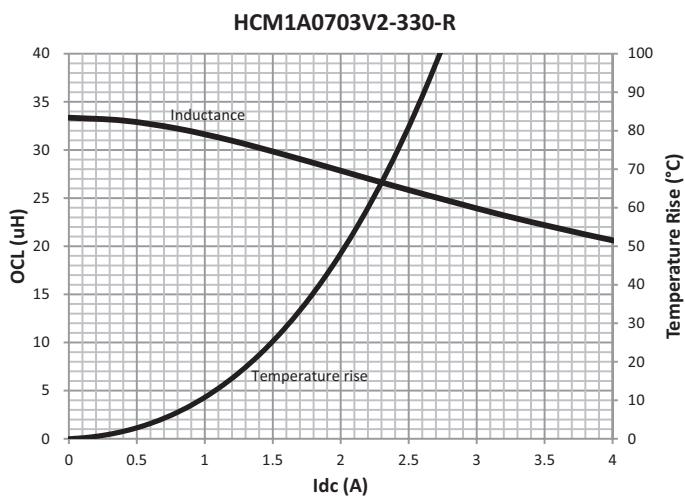
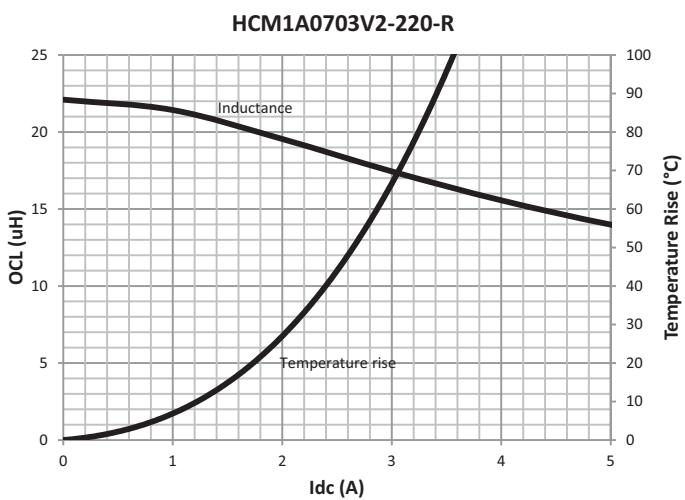
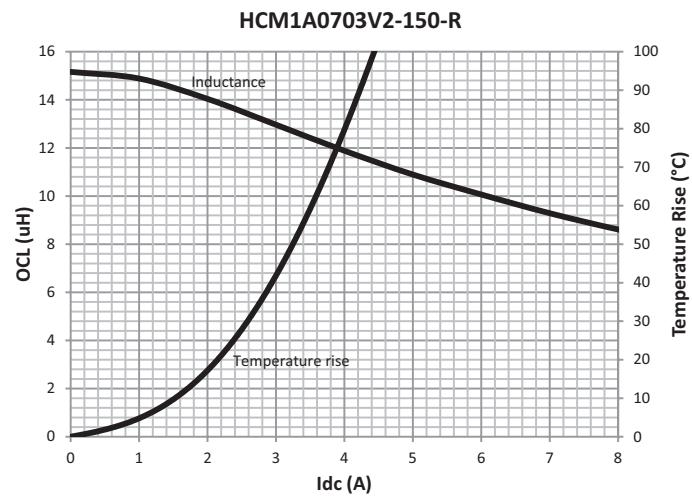
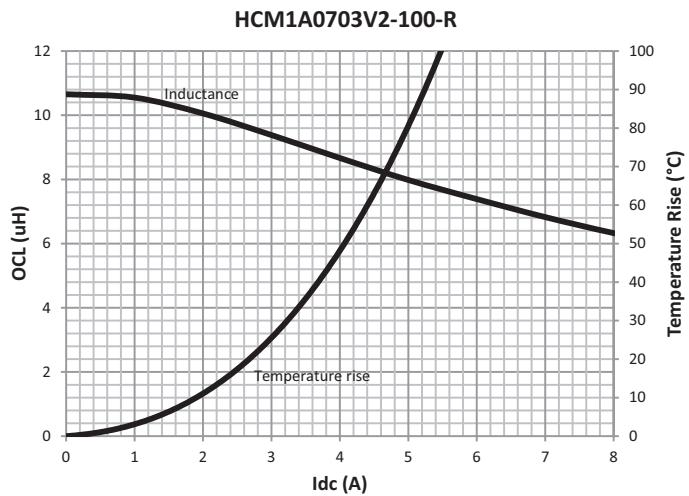


**Inductance and temperature rise vs. current**

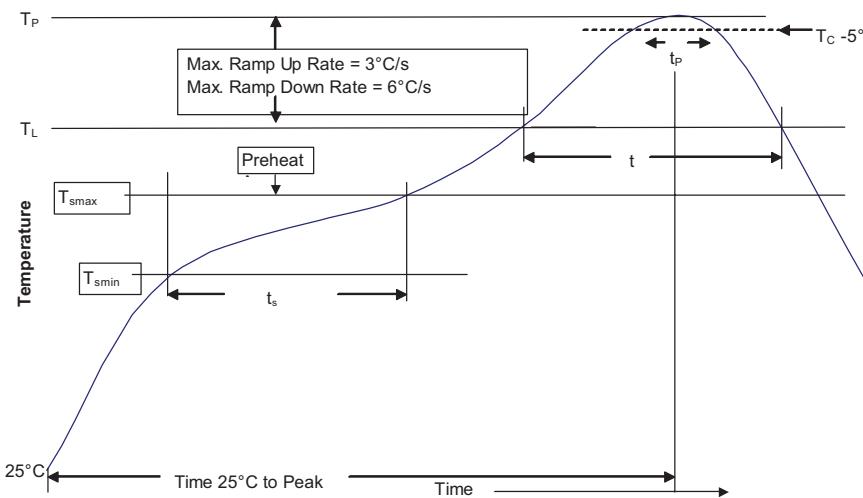


**Inductance and temperature rise vs. current**



**Inductance and temperature rise vs. current**

## Solder reflow profile



**Table 1 - Standard SnPb Solder ( $T_c$ )**

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> ≥350
<2.5 mm)	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

**Table 2 - Lead (Pb) Free Solder ( $T_c$ )**

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350 - 2000	Volume mm <sup>3</sup> >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 – 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

## Reference J-STD-020

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak	<ul style="list-style-type: none"> <li>Temperature min. (<math>T_{smin}</math>)</li> <li>Temperature max. (<math>T_{smax}</math>)</li> </ul>	100 °C
Average ramp up rate $T_{smax}$ to $T_p$	3°C/ Second Max.	3 °C/ Second Max.
Liquidous temperature ( $T_L$ )	183 °C	217 °C
Time at liquidous ( $t_L$ )	60-150 Seconds	60-150 Seconds
Peak package body temperature ( $T_p$ )*	Table 1	Table 2
Time ( $t_p$ )** within 5 °C of the specified classification temperature ( $T_c$ )	20 Seconds**	30 Seconds**
Average ramp-down rate ( $T_p$ to $T_{smax}$ )	6 °C/ Second Max.	6 °C/ Second Max.
Time 25 °C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

\* Tolerance for peak profile temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.

\*\* Tolerance for time at peak profile temperature ( $t_p$ ) is defined as a supplier minimum and a user maximum.

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